

2026 IEEE 18th International Conference on Solid-State and Integrated Circuit Technology (ICSICT)

🕒 Oct. 27 - 30, 2026 📍 Hangzhou, China

Conference Website: www.icsict.org

ICSICT 2026 ABOUT CONFERENCE //

2026 IEEE 18th International Conference on Solid-State and Integrated Circuit Technology (ICSICT) in the series aiming to provide an international forum for the presentation and discussion of recent advances in solid-state and integrated circuit technology. The conference will be held on Oct. 27 - 30, 2026 in Hangzhou, China. All aspects of solid-state devices, circuits and systems, process technologies, materials and other related research are within the scope of the conference. Over the course of four days, a rich program of contributed and invited presentations will cover the latest advancements in various fields. These presentations will be delivered through both oral and poster sessions, accompanied by panel discussions addressing cutting-edge technology issues and various engaging activities. This comprehensive program aims to foster extensive opportunities for the exchange of technical information and create a stimulating atmosphere for mutual communication among all participants. The presentation of the Excellent Student Paper Award and the Outstanding Young Scholar Paper Award will take place during the conference's closing ceremony. Enterprises with relevance to the event are encouraged to join and actively take part in the exhibition.

ICSICT 2026 CO-SPONSORED BY //



ICSICT 2026 TECHNICALLY CO-SPONSORED BY //



ICSICT 2026 HOSTED BY //



ICSICT 2026 PATRONS //



ICSICT 2026 CONFERENCE COMMITTEE //

- Life Honorary Chair**
Yangyuan Wang, Peking University, China
- Advisory Committee Co-Chairs**
Ting-Ao Tang, Fudan University, China
Cor Claey's, Proximus, Belgium
Mengqi Zhou, IEEE China Council, China
- General Chairs**
Jan Van der Spiegel, University of Pennsylvania, USA
Bin Zhao, IEEE EDS, USA
Francois Rivet, University of Bordeaux, France
Amara Amara, International Innovation Institute, Beihang University, Hangzhou Campus, China
- General Co-Chairs**
Ning Xu, Wuhan University of Technology, China
Cheng Zhuo, Zhejiang University, China
Yuehang Xu, Yangtze Delta Region Institute of University of Electronic Science and Technology of China, Huzhou, China
Gaofeng Wang, Hangzhou Dianzi University, China
- Technical Program Committee Chairs**
Haruo Kobayashi, Gunma University, Japan
Ming Li, Peking University, China
Bo Zhang, University of Electronic Science and Technology of China, China
Yi Zhao, Huada Semiconductor
- Technical Program Committee Co-Chairs**
Bei Yu, The Chinese University of Hong Kong, China
Zheng Wang, University of Electronic Science and Technology of China, China
Fakhrul Zaman Rokhani, Universiti Putra Malaysia, Malaysia
Ling Zhang, Zhejiang University, China
Yuchao Yang, Peking University, China
Jing Jin, Shanghai Jiao Tong University, China
Wentong Zhang, University of Electronic Science and Technology of China, China
Haifeng Ling, Nanjing University of Posts and Telecommunications, China
- Local Arrangement Chair**
Letian Huang, Yangtze Delta Region Institute of University of Electronic Science and Technology of China, Huzhou, China
- Subcommittee Chairs**
Haifeng Ling, Nanjing University of Posts and Telecommunications, China
Wentong Zhang, University of Electronic Science and Technology of China, China
Jing Jin, Shanghai Jiao Tong University, China
Yuchao Yang, Peking University, China
- Subcommittee Co-Chairs**
Hailong Jiao, Peking University, China
Zheng Wang, University of Electronic Science and Technology of China, China
Jin Wei, Peking University, China
Zhihao Yu, Nanjing University of Posts and Telecommunications, China
- Special Session Chair**
Haimeng Huang, University of Electronic Science and Technology of China, China
- Tutorial Chair**
Wei Mao, Xidian University, China
- Industry Liaison Chairs**
Sylvain Eimer, Truth Equipment, China
Preet Yadav, NXP Semiconductors, India
- Publicity Co-Chairs**
Caoyu Li, Yangtze Delta Region Institute of University of Electronic Science and Technology of China, Huzhou, China
Chaoyue Zheng, Yangtze Delta Region Institute of University of Electronic Science and Technology of China, Huzhou, China
- Publication Committee Chair**
Mengqi Zhou, IEEE China Council, China
- Publication Committee Co-chairs**
Lobna A. Said, Nile University, Egypt
Guoqing Deng, Sichuan Institute of Electronics, China
- Publication Committee Chair**
Mengqi Zhou, IEEE China Council, China
- Publication Committee Co-chair**
Guoqing Deng, Sichuan Institute of Electronics, China
- Treasurer**
Jianhong Zhou, Xihua University, China
- Secretary General**
Tiantian Han, Yangtze Delta Region Institute of University of Electronic Science and Technology of China, Huzhou, China

ICSICT 2026 CONFERENCE SCOPE //

Paper submissions are solicited in, but not limited to the following areas:

- Theme 1: Digital & System Level IC**
Chair: Yuchao Yang, Peking University, China
Co-Chair: Hailong Jiao, Peking University, China
- Track 1: Digital Architectures & Systems**
Chair: Zhiyi Yu, Sun Yat-sen University, China
Co-Chairs: Yaoyu Tao, Peking University, China
Hongyang Jia, Tsinghua University, China
- Track 2: Digital Circuits**
Chair: Yongpan Liu, Tsinghua University, China
Co-Chairs: Yanan Sun, Shanghai Jiao Tong University, China
Fengbin Tu, Hong Kong University of Science and Technology, China
- Track 3: Design Methodology & EDA**
Chair: Jun Yang, Southeast University, China
Co-Chairs: Yibo Lin, Peking University, China
Yu Li, Zhejiang University, China
- Theme 2: Analog**
Chair: Jing Jin, Shanghai Jiao Tong University, China
Co-Chair: Zheng Wang, University of Electronic Science and Technology of China, China
- Track 4: RF & Wireless**
Chair: Keping Wang, Tianjin University, China
Co-Chairs: Jian Pang, Shanghai Jiao Tong University, China
Kai Tang, Hunan University, China
- Track 5: Wireline**
Chair: Xiaoyan Gui, Xi'an Jiaotong University, China
Co-Chairs: Bingyi Ye, East China Normal University, China
Yuekang Guo, Shanghai Jiao Tong University, China
- Track 6: General Analog**
Chair: Lin Cheng, University of Science and Technology of China, China
Co-Chairs: Junmin Jiang, Southern University of Science and Technology, China
Ang Hu, Huazhong University of Science and Technology, China
- Theme 3: Devices**
Chair: Wentong Zhang, University of Electronic Science and Technology of China, China
Co-Chair: Jin Wei, Peking University, China
- Track 7: CMOS Logic Devices & Sensors**
Chair: Heng Wu, Peking University, China
Co-Chairs: Wang Kang, Beihang University, China
Xiaosheng Zhang, University of Electronic Science and Technology of China, China
- Track 8: Power Devices & Power IC**
Chair: Long Zhang, Southeast University, China
Co-Chairs: Jiafei Yao, Nanjing University of Posts and Telecommunications, China
Zekun Zhou, University of Electronic Science and Technology of China, China
- Track 9: Device Reliability & Security**
Chair: Mengyuan Hua, Southern University of Science and Technology, China
Co-Chairs: Sen Huang, Institute of Microelectronics of Chinese Academy of Sciences, China
Zhao Qi, University of Electronic Science and Technology of China, China
- Theme 4: Process & Technologies**
Chair: Haifeng Ling, Nanjing University of Posts and Telecommunications, China
Co-Chair: Zhihao Yu, Nanjing University of Posts and Telecommunications, China
- Track 10: Semiconductor Process Technologies**
Chair: Bobo Tian, East China Normal University, China
Co-Chairs: Min Liao, Xidian University, China
Li Zhu, Nanjing University of Posts and Telecommunications, China
- Track 11: Optoelectronics and Silicon Photonics Integration**
Chair: Linfeng Sun, Beijing Institute of Technology, China
Co-Chairs: Ming Xu, Huazhong University of Science and Technology, China
Yuanfang Yu, Nanjing University of Posts and Telecommunications, China
- Track 12: Packaging Technologies**
Chair: Jun Zhang, Nanjing University of Posts and Telecommunications, China
Co-Chairs: Shenyang Mo, NARI Semiconductor R&D Center, China
Pengfei Zhao, Nanjing University of Posts and Telecommunications, China

ICSICT 2026 PAPER SUBMISSION //

Prospective authors are requested to submit **at least 3 pages camera-ready full length paper in English**. Accepted papers will be included in conference proceedings.

Submission System



The submission system for ICSICT 2026 has been opened. Welcome to submit papers through:
<https://easychair.org/conferences/?conf=icsict2026>

Important Dates

| | |
|-------------------------------|---------------|
| Deadline for Paper Submission | June 25, 2026 |
| Notification of Acceptance | July 25, 2026 |

* Visit the following page to view the detail submission guidelines: <https://www.icsict.org/Submission.html>